

Thermal Characteristics								
Parameter		Symbol	Тур	Max	Units			
Maximum Junction-to-Ambient A	t ≤ 10s	R <sub>0JA</sub>	31	40	°C/W			
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State	κ <sub>θJA</sub>	59	75	°C/W			
Maximum Junction-to-Lead <sup>C</sup>	Steady-State	$R_{ ext{ hetaJL}}$	16	24	°C/W			

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
STATIC I	PARAMETERS	·	·			
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	30			V
I <sub>DSS</sub> Z	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			1	μA
		T <sub>J</sub> =55°0	5°C		5	
I <sub>GSS</sub>	Gate-Body leakage current	$V_{DS}$ =0V, $V_{GS}$ = ±12V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_{D}=250\mu A$	1	1.8	3	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V	30			Α
R <sub>DS(ON)</sub> s	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A		22	26	-mΩ
		T <sub>J</sub> =12	5°C			
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A		28	34	mΩ
<b>g</b> <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =5A				S
$V_{SD}$	Diode Forward Voltage	Is=1A,V <sub>GS</sub> =0V		0.76	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				4	А
DYNAMI	C PARAMETERS					
C <sub>iss</sub>	Input Capacitance			590		pF
C <sub>oss</sub>	Output Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		162		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			40		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		0.45		Ω
SWITCHI	NG PARAMETERS					
Q <sub>g</sub>	Total Gate Charge			6.04		nC
Q <sub>gs</sub>	Gate Source Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =15V, I <sub>D</sub> =8.5A		1.46		nC
Q <sub>gd</sub>	Gate Drain Charge			2.56		nC
t <sub>D(on)</sub>	Turn-On DelayTime			3.7		ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =1.8Ω	,	3.5		ns
t <sub>D(off)</sub>	Turn-Off DelayTime	$R_{GEN}=3\Omega$		14.9		ns
t <sub>f</sub>	Turn-Off Fall Time			2.5		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =5A, dI/dt=100A/μs				ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =5A, dI/dt=100A/μs				nC

A: The value of  $R_{0JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The value in any a given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating. B: Repetitive rating, pulse width limited by junction temperature.

C. The R  $_{\rm 0JA}$  is the sum of the thermal impedence from junction to lead R  $_{\rm 0JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using  $80\mu$ s pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The SOA curve provides a single pulse rating.